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(71) Applicant: **SILICONWARE PRECISION INDUSTRIES CO., LTD.**, Taichung (TW)

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(72) Inventors: **Chih-Hsien CHIU**, Taichung (TW); **Wen-Jung TSAI**, Taichung (TW); **Wei-Hao LI**, Taichung (TW); **Chih-Yi LIAO**, Taichung (TW); **Cheng-Wei HSU**, Taichung (TW); **Chih-Yuan TSAI**, Taichung (TW); **Ko-Wei CHANG**, Taichung (TW); **Guo-Yu WU**, Taichung (TW)

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(73) Assignee: **SILICONWARE PRECISION INDUSTRIES CO., LTD.**, Taichung (TW)

(57) **ABSTRACT**

An electronic package is provided, in which an electronic element is disposed on a carrier with a circuit layer, and an encapsulation layer encapsulating the electronic element has an opening exposing the circuit layer, where a metal structure can be contact-bonded on a wall surface of the opening, and a conductive element is formed on the metal structure and electrically connected to the circuit layer. Therefore, no gap is formed between the conductive element and the wall surface of the opening, such that the DC resistance of the conductive element can be reduced.

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